12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130110002

Qualification of TI Philippines as an alternate assembly site for selected devices in the HTQFP package family

Change Notification / Sample Request

Date: 1/14/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI’s standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130110002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TAS5717PHPR	null
TAS5719PHP	null
TAS5727PHP	null
TAS5731PHP	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130110002	**PCN Date:**	01/14/2013
Title:	Qualification of TI Philippines as an alternate assembly site for selected devices in the HTQFP package family		

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	04/14/2013	**Estimated Sample Availability:**	02/28/2013		

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of TI Philippines as an alternate assembly site for selected devices in the HTQFP package family. The material set will remain the same between the 2 sites:

	TI Taiwan-AT	**TI Philippines-AT**
Mold Compound	4205443	**4205443**
Mount Compound	4208458	**4208458**
Bond Wire	1.98/0.8 Mil Dia., Cu	**1.98/0.8 Mil Dia., Cu**

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI
TI Philippines	Assembly Site Origin (22L)	ASO: PHI

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:
Assembly site code for TI Taiwan = T
Assembly site code for TI Philippines = W

Product Affected:

TAS5717LPHP	TAS5719PHP	TAS5731PHP	TAS5735PHP
TAS5717LPHPR	TAS5719PHPR	TAS5731PHPR	TAS5735PHPR
TAS5717PHP	TAS5727PHP	TAS5733PHP	TAS5745PHP
TAS5717PHPR	TAS5727PHPR	TAS5733PHPR	TAS5745PHPR

Qualification Plan

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Schedule:	**Start:**	January 2013	**End:**	March 2013

Qualification Device: TAS5745PHP (MSL 3-260C)

Package Construction Details

Assembly Site:	TI Philippines	Mold Compound:	4205443
# Pins-Designator, Family:	48-PHP, HTQFP	Mount Compound:	4208458
Lead Finish:	NiPdAu	Bond Wire:	1.98/0.8 Mil Dia., Cu

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
Electrical Characterization	(To Datasheet parameters)	30/0	--	--
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0
Manufacturability (Assembly)	(per mfg. Site specification)	3/0	--	--
Moisture Sensitivity	(level 3 @ 260C +5/-0C)	12/0	12/0	12/0

Notes: **Tests require preconditioning sequence: MSL3-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com